



TOHOKU  
UNIVERSITY

# 2019 Spintronics Workshop on LSI

Sunday, June 9, 2019, 19:00 – 22:00

Rihga Royal Hotel Kyoto, Suzaku III (2F), Kyoto, Japan

[http://www.cies.tohoku.ac.jp/2019\\_Spintronics\\_WS/](http://www.cies.tohoku.ac.jp/2019_Spintronics_WS/)



## General Information

The 2019 Spintronics Workshop on LSI will be held at Rihga Royal Hotel Kyoto, Kyoto, Japan, on June 9, 2019 as a Satellite Workshop of 2019 Symposia on VLSI Technology and Circuits. The workshop will focus on spintronics-based LSI technologies for high performance and ultra low power systems. Papers on current status, prospects and the remaining challenges in this field will be presented from invited speakers. The workshop is sponsored by Center for Innovative Integrated Electronic Systems (CIES), Center for Science and Innovation in Spintronics (CSIS) and Center for Spintronics Research Network (CSRN), Tohoku University.

## Registration

The workshop fee is free of charge, but registration is required.

[http://www.cies.tohoku.ac.jp/2019\\_Spintronics\\_WS/](http://www.cies.tohoku.ac.jp/2019_Spintronics_WS/)

Deadline of advanced registration:

June 7th, 2019

Registration desk open at 6:30pm

## Program

19:00-19:05	Opening remarks: Tetsuo Endoh (Tohoku University, Workshop Program Chair)
19:05-19:35	<b>Invited talk 1</b> Yoonjong Song (Samsung) Recent progress in embedded STT-MRAM technology
19:35-20:05	<b>Invited talk 2</b> William Gallagher (TSMC) Recent progress and next directions for embedded MRAM technology
20:05-20:35	<b>Invited talk 3</b> Hideo Sato (Tohoku Univ.) 128Mb STT-MRAM with high performance and high endurance by an integration process development
20:35-21:05	<b>Invited talk 4</b> Shigeki Tomishima (Intel) The Spintronics Memory Positioning in AI Computing Systems
21:05-21:35	<b>Invited talk 5</b> Danny Shum (NXP) Embedded MRAM development for industrial MCU/IoT applications
21:35-21:45	Closing remarks: Tetsuo Endoh (Tohoku University, Workshop Program Chair)

## Committee

<b>Program Chair</b>	Tetsuo Endoh	Tohoku Univ.
<b>Program Committee</b>	Tadahiro Kuroda	Keio Univ., JSAP Executive Committee Chair of 2019 Symposia on VLSI Technology and Circuits
	H. S. Philip Wong	Stanford Univ., TSMC, IEEE Executive Committee Chair of 2019 Symposia on VLSI Technology and Circuits
	Shoji Ikeda	Tohoku Univ.
	Takahiro Hanyu	Tohoku Univ.
	Masaaki Niwa	Tohoku Univ., JSAP Executive Committee Member of 2019 Symposia on VLSI Technology and Circuits

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